

1. General description

Planar passivated high commutation three quadrant triac in a SOT226A (I2PAK) plastic package intended for use in circuits where high static and dynamic dV/dt and high dI/dt can occur. This "series CT" triac will commute the full RMS current at the maximum rated junction temperature ($T_{j(max)} = 150\text{ °C}$) without the aid of a snubber. It is used in applications where "high junction operating temperature capability" is required.

2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High junction operating temperature capability ($T_{j(max)} = 150\text{ °C}$)
- High voltage capability
- Less sensitive gate for high noise immunity
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- Very high immunity to false turn-on by dV/dt
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant

3. Applications

- Applications subject to high temperature
- Electronic thermostats (heating and cooling)
- High power motor controls e.g. washing machines and vacuum cleaners
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

4. Quick reference data

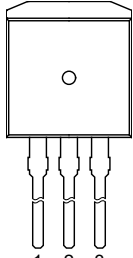

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 118\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	-	-	12	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5	-	-	100	A
		full sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$	-	-	110	A
T_j	junction temperature		-	-	150	°C
Static characteristics						

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _{GT}	gate trigger current	V _D = 12 V; I _T = 100 mA; T2+ G+; T _j = 25 °C; Fig. 7	-	-	35	mA
		V _D = 12 V; I _T = 100 mA; T2+ G-; T _j = 25 °C; Fig. 7	-	-	35	mA
		V _D = 12 V; I _T = 100 mA; T2- G-; T _j = 25 °C; Fig. 7	-	-	35	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; Fig. 9	-	-	35	mA
V _T	on-state voltage	I _T = 15 A; T _j = 25 °C; Fig. 10	-	-	1.6	V
Dynamic characteristics						
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 402 V; T _j = 150 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit	300	-	-	V/μs
di _{com} /dt	rate of change of commutating current	V _D = 400 V; T _j = 150 °C; I _{T(RMS)} = 12 A; dV _{com} /dt = 20 V/μs; (snubberless condition); gate open circuit	8	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1	 <p>I2PAK (SOT226A)</p>	 <p>sym051</p>
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BTA312G-600CT	I2PAK	plastic single-ended package (I2PAK); TO-262	SOT226A

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	600	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 118\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	-	12	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 20\text{ ms}$; Fig. 4 ; Fig. 5	-	100	A
		full sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 16.7\text{ ms}$	-	110	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine-wave pulse	-	50	A ² s
di_T/dt	rate of rise of on-state current	$I_G = 70\text{ mA}$	-	100	A/ μ s
I_{GM}	peak gate current	$t = 20\text{ }\mu$ s	-	2	A
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T_{stg}	storage temperature		-40	150	°C
T_j	junction temperature		-	150	°C

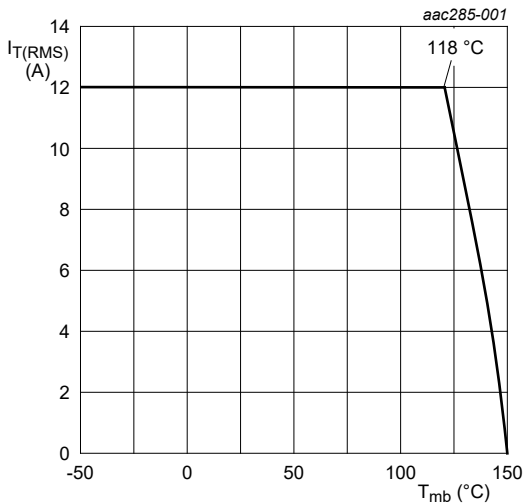
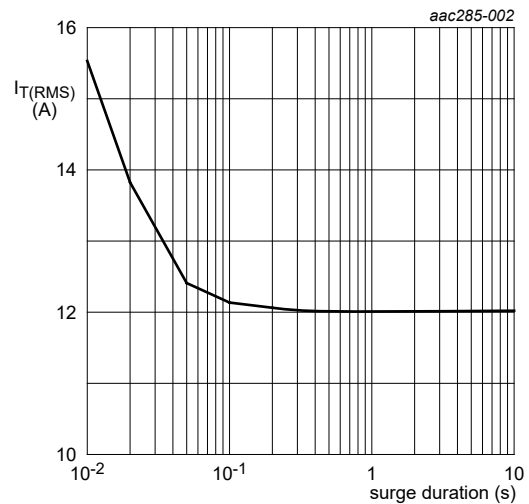


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values



$f = 50\text{ Hz}$; $T_{mb} = 118\text{ °C}$

Fig. 2. RMS on-state current as a function of surge duration; maximum values

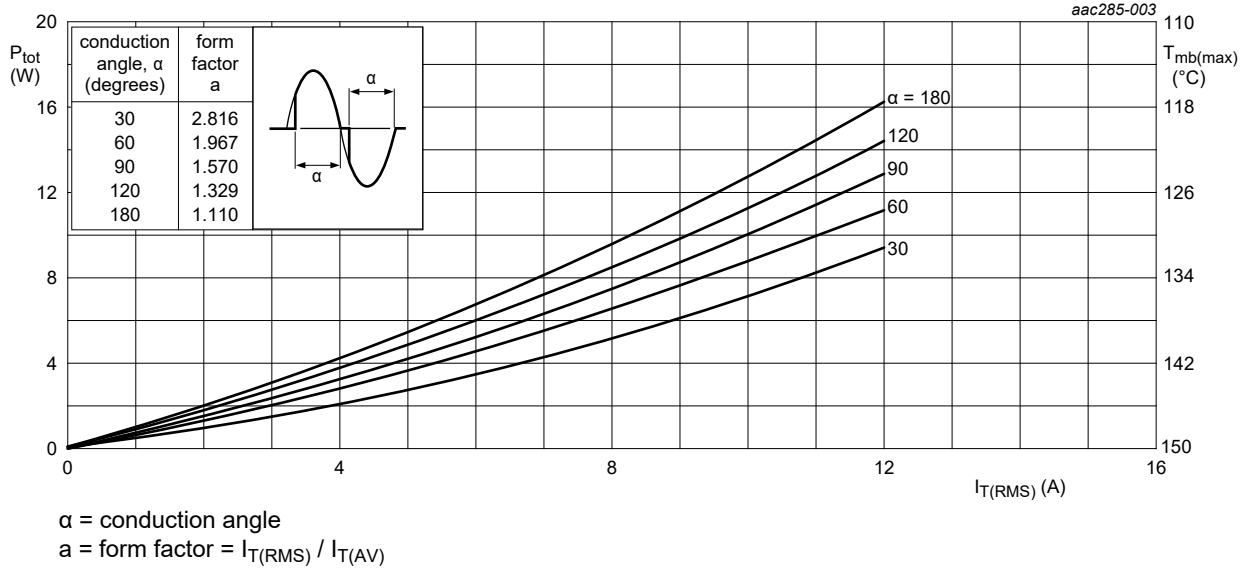


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

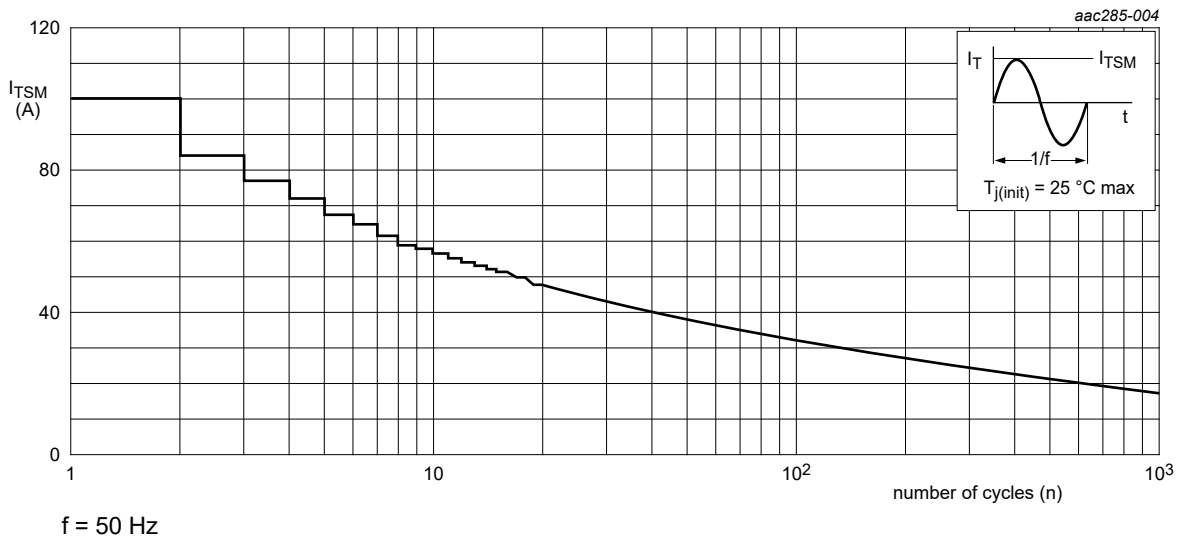
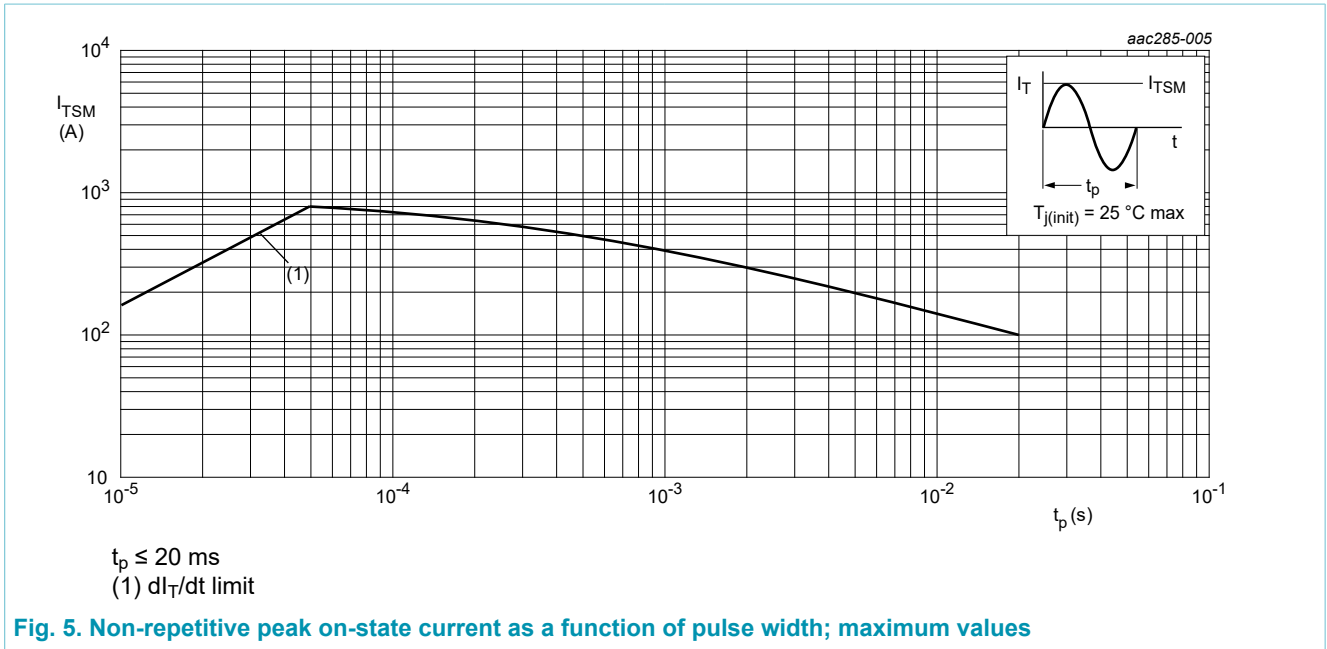


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	half cycle; Fig. 6	-	-	2.4	K/W
		full cycle; Fig. 6	-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

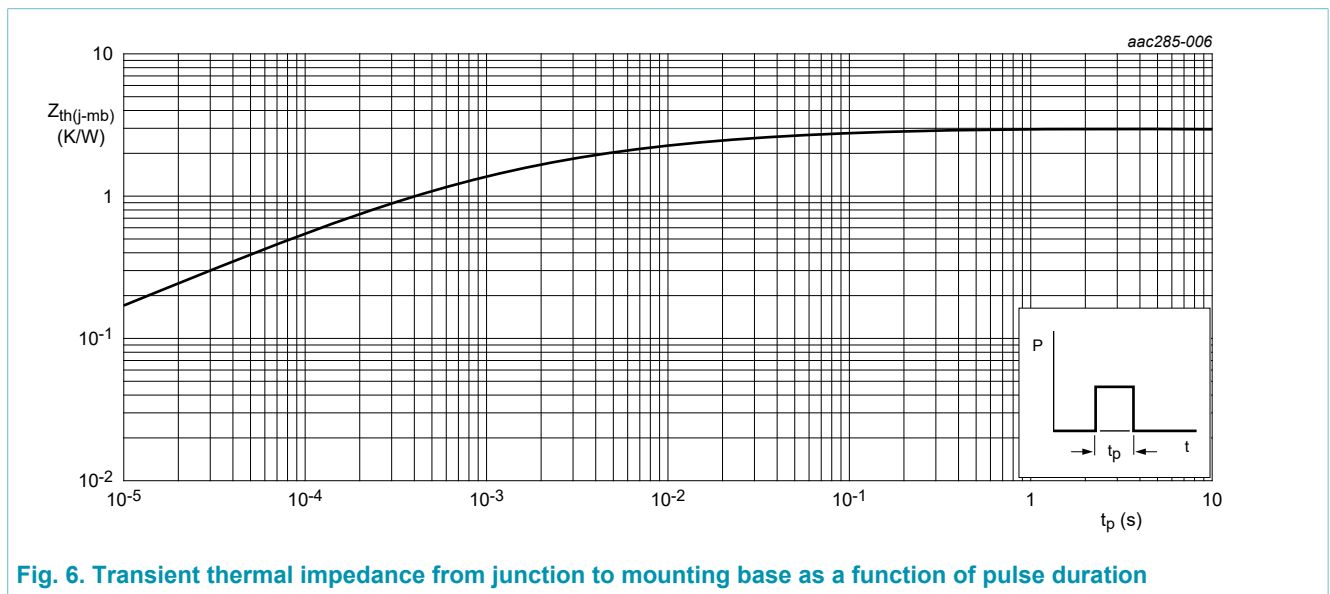
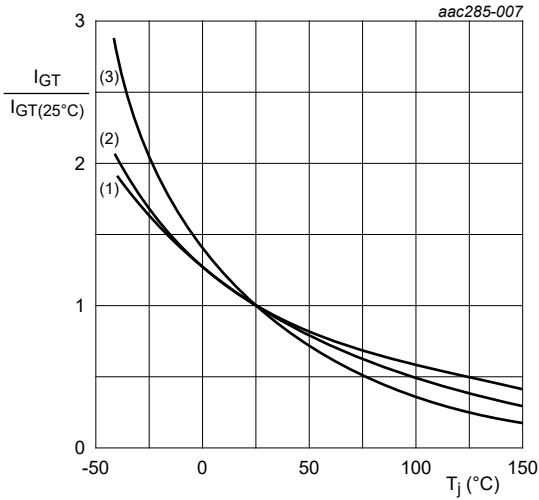


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CL}	clamping voltage		-	-	-	
di_{com}/dt	rate of change of commutating current		-	-	-	
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}; I_T = 100\text{ mA}; T_2+ G+;$ $T_j = 25\text{ °C};$ Fig. 7	-	-	35	mA
		$V_D = 12\text{ V}; I_T = 100\text{ mA}; T_2+ G-;$ $T_j = 25\text{ °C};$ Fig. 7	-	-	35	mA
		$V_D = 12\text{ V}; I_T = 100\text{ mA}; T_2- G-;$ $T_j = 25\text{ °C};$ Fig. 7	-	-	35	mA
I_L	latching current	$V_D = 12\text{ V}; I_G = 100\text{ A}; T_2+ G+;$ $T_j = 25\text{ °C};$ Fig. 8	-	-	50	mA
		$V_D = 12\text{ V}; I_G = 100\text{ A}; T_2+ G-;$ $T_j = 25\text{ °C};$ Fig. 8	-	-	60	mA
		$V_D = 12\text{ V}; I_G = 100\text{ A}; T_2- G-;$ $T_j = 25\text{ °C};$ Fig. 8	-	-	50	mA
I_H	holding current	$V_D = 12\text{ V}; T_j = 25\text{ °C};$ Fig. 9	-	-	35	mA
V_T	on-state voltage	$I_T = 15\text{ A}; T_j = 25\text{ °C};$ Fig. 10	-	-	1.6	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}; I_T = 100\text{ mA}; T_j = 25\text{ °C};$ Fig. 11	-	0.8	1	V
		$V_D = 400\text{ V}; I_T = 100\text{ mA}; T_j = 150\text{ °C};$ Fig. 11	0.2	0.45	-	V
I_D	off-state current	$V_D = 600\text{ V}; T_j = 25\text{ °C}$	-	-	10	μA
		$V_D = 600\text{ V}; T_j = 150\text{ °C}$	-	0.4	2	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}; T_j = 150\text{ °C}; (V_{DM} = 67\%$ of $V_{DRM});$ exponential waveform; gate open circuit	300	-	-	V/ μs
di_{com}/dt	rate of change of commutating current	$V_D = 400\text{ V}; T_j = 150\text{ °C}; I_{T(RMS)} = 12\text{ A};$ $dV_{com}/dt = 20\text{ V}/\mu\text{s};$ (snubberless condition); gate open circuit	8	-	-	A/ms
			-	-	-	



- (1) T2+ G+
- (2) T2+ G-
- (3) T2- G-

Fig. 7. Normalized gate trigger current as a function of junction temperature

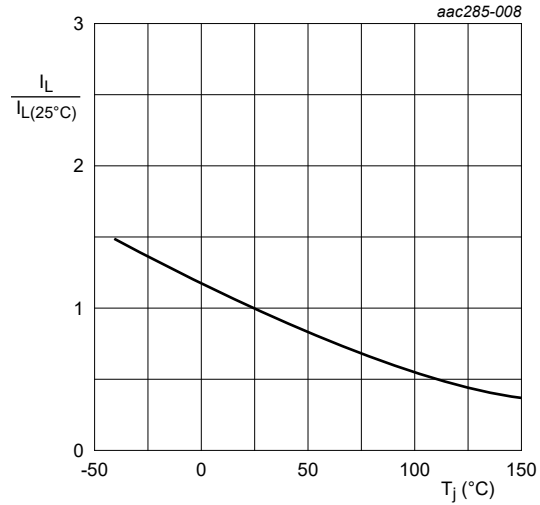


Fig. 8. Normalized latching current as a function of junction temperature

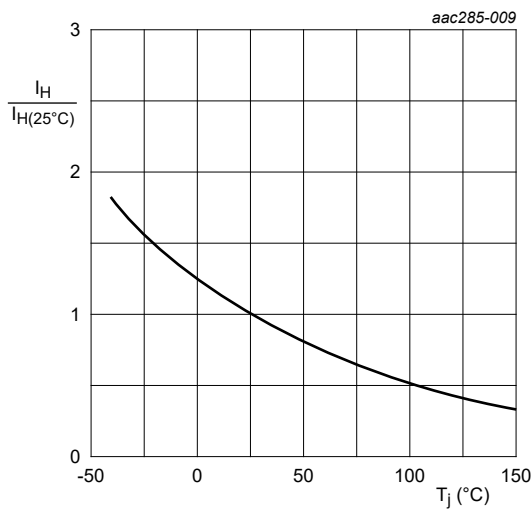
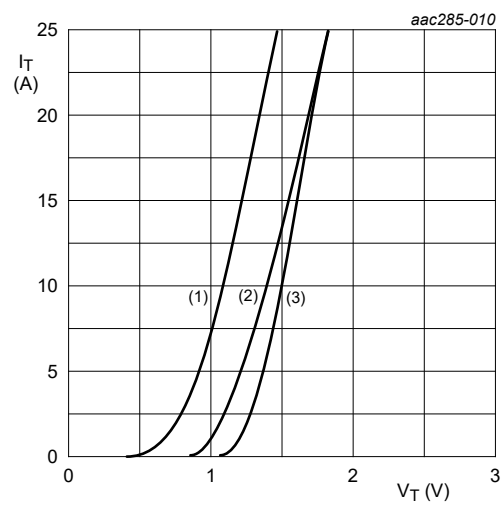


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.037 \text{ V}; R_s = 0.034 \Omega$

- (1) $T_j = 150^\circ\text{C}$; typical values
- (2) $T_j = 150^\circ\text{C}$; maximum values
- (3) $T_j = 25^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

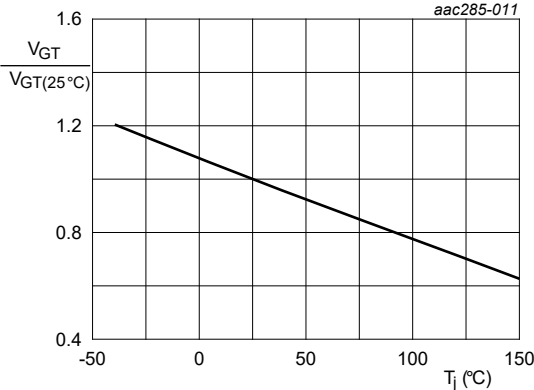
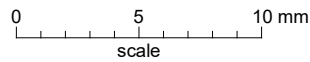
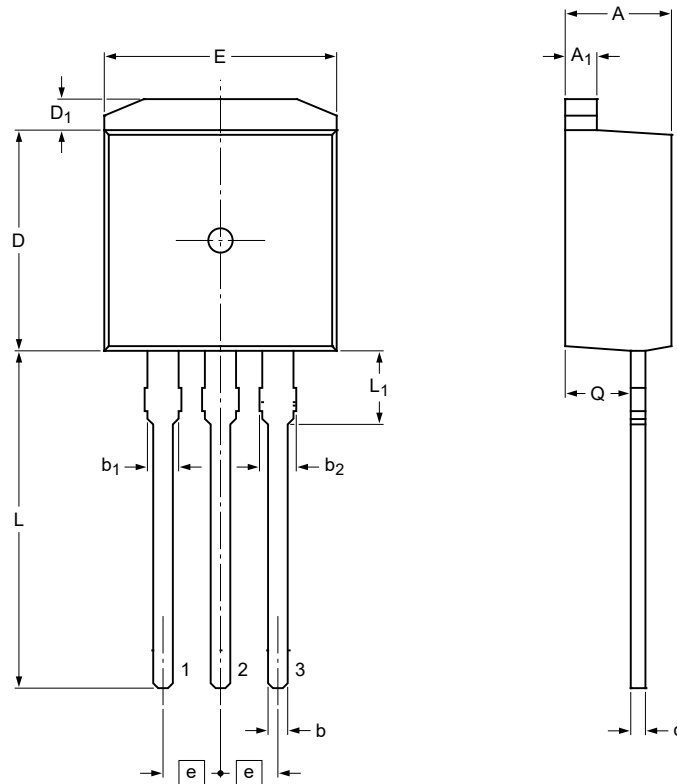


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

10. Package outline

Plastic single-ended package (I2PAK); low-profile 3-lead TO-262

SOT226A



Dimensions

Unit	A	A ₁	b	b ₁	b ₂	c	D	D ₁	E	e	L	L ₁	Q
max	4.7	1.40	0.95	1.40	1.7	0.65	9.4	1.32	10.30	2.54	15.0	3.0	2.6
nom										(REF)		(REF)	
min	4.3	1.15	0.70	1.14	1.3	0.45	8.6	1.02	9.65		12.5		2.2

sot226a_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT226A		TO-262			09-08-17 09-08-25

Fig. 12. Package outline I2PAK (SOT226A)

11. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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